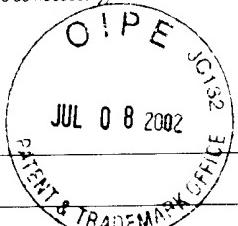


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Sheet 1 of 1

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Complete if Known	
Application Number	09/652430
Filing Date	September 1, 2000
First Named Inventor	Sur, Biswajit
Group Art Unit	2835
Examiner Name	Lea-Edmonds, Lisa

Attorney Docket No: 00884.319US1

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Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date If Appropriate
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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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EXAMINER

Andy Kewell

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